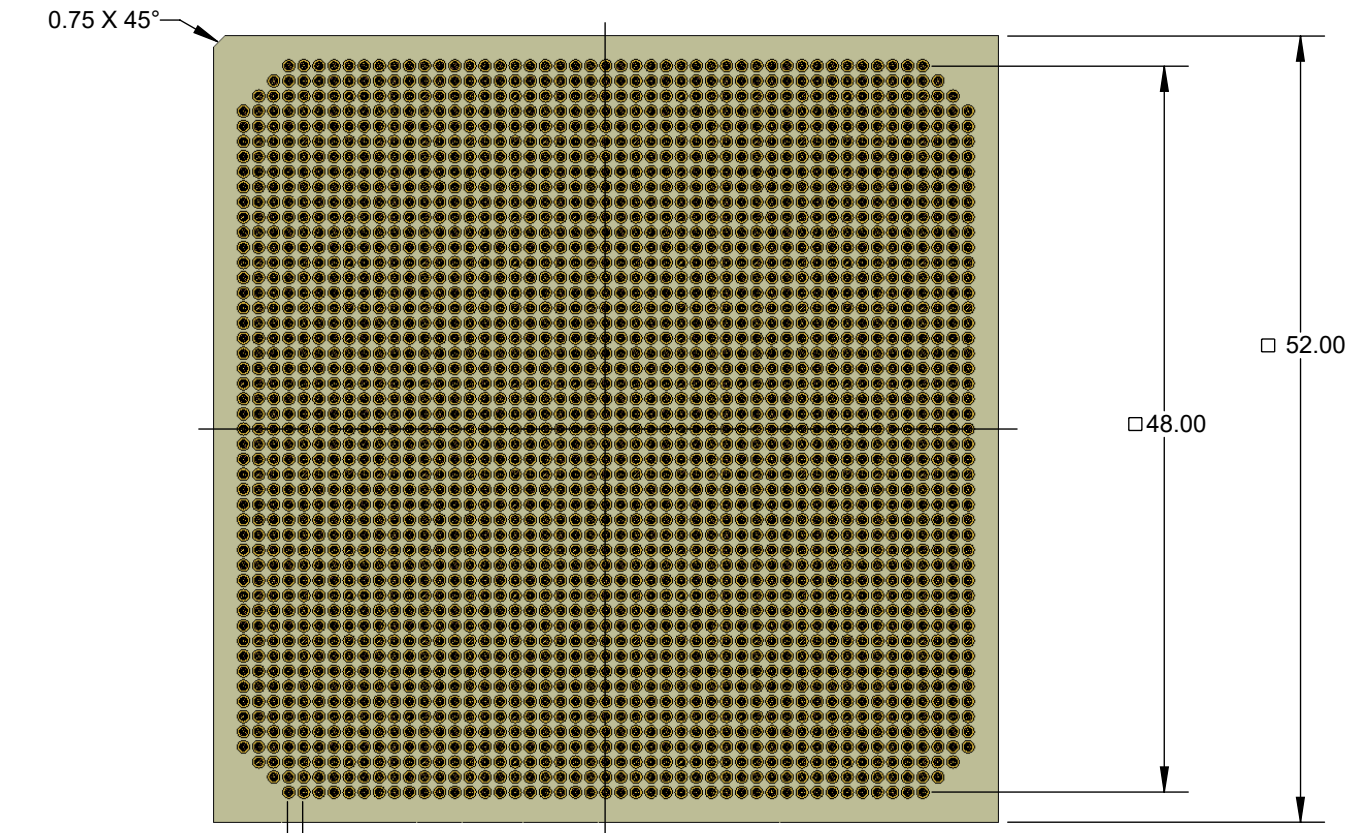
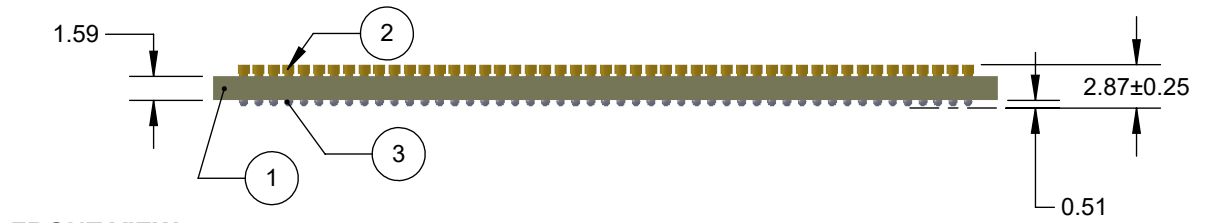


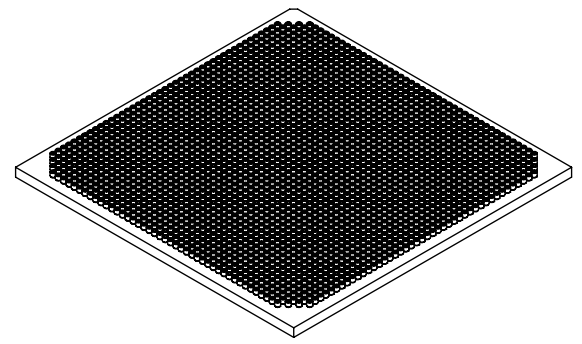
U.S. Patent No. 8,091,222 B2



TOP VIEW



FRONT VIEW




SCALE 1 : 1

ITEM NO.	Description	Material
1	Substrate, 2377 holes	FR4 Standard
2	Receptacle Pin	Body - Gold Plated Brass 360, Clip - Gold plated Beryllium Copper 172
3	Solder Ball, ROHS Compliant 0.024" Dia	Sn96.5 Ag3.0 Cu0.5

Description: BGA Surface mount emulator foot

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.
 Tolerances: Hole diameters $\pm 0.0254\text{mm}$ [$\pm 0.001"$], Pitches (from true position) $\pm 0.0254\text{mm}$ [$\pm 0.001"$], substrate thickness tolerance $\pm 10\%$, all other tolerances $\pm 0.127\text{mm}$ [$\pm 0.005"$] unless stated otherwise. Materials and specifications are subject to change without notice.

SF-BGA2377A-B-42F Drawing  ©2015 Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com	Material: N/A Finish: N/A Weight: 15.25	STATUS: Released	SHEET: 1 OF 1	REV. A
		ENG: E. Smolentseva	DRAWN BY: M. Raske	SCALE: 2:1
		FILE: SF-BGA2377A-B-42F Dwg	DATE: 01/27/2016	